

Specialized Thermal Interface Material

Thermally Conductive Dispensable Jelly



MATERIAL

Gap filler jelly



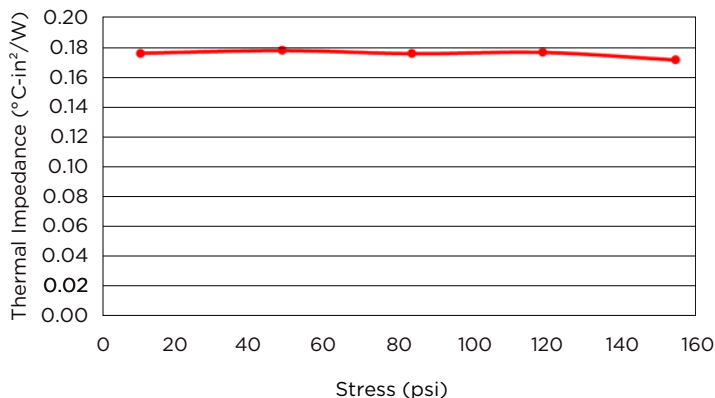
FEATURES

- Ideal for high-frequency RF applications
- Works well in vertical and high vibration environments
- Easily dispensable; fast-curing in room temperature
- Gel-like, less stress, easy rework
- Long-term reliability in harsh environments
- 3.5 W/m-K Thermal conductivity

Thermal Impedance Vs. Stress of T-CIP-35 (1 mm thick)

(@ 60°C: Step application of pressure
11, 46, 82, 118, 154 psi; ASTM D5470 modified)

— T-CIP-35



PROPERTIES	T-CIP-35
Composition	Gap filler jelly
Viscosity @ 25°C (Pa·s)	Part A: 5000 / Part B: 5000
Specific Gravity @ 25°C	Part A: 2.54 / Part B: 2.54
Mix Ratio (2-part)	1:1
Mixed Viscosity @ 25°C	>5000 Pa·s
Tack-Free Time*	1 hr
Curing Conditions	4 hrs under 25 °C
Softness	40 Shore OO
Tensile Strength	0.08 MPa
Dielectric Breakdown Strength	10 kV/mm
Volume Resistance	4 TΩ·cm
Thermal Conductivity	3.5 W/m-K

* The time while the material is malleable.

GET IN TOUCH

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